

10

9

8

7

6

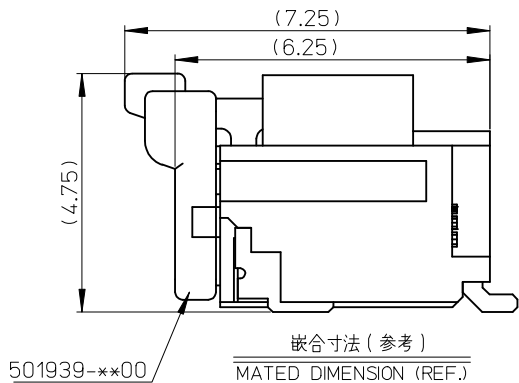
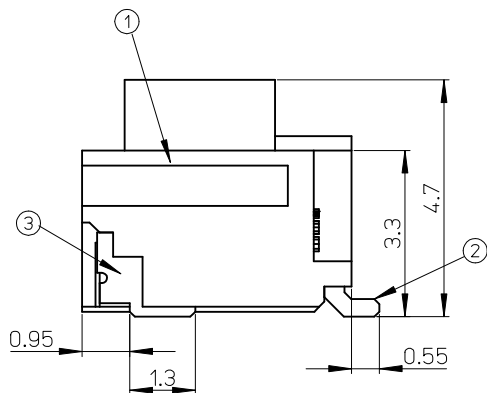
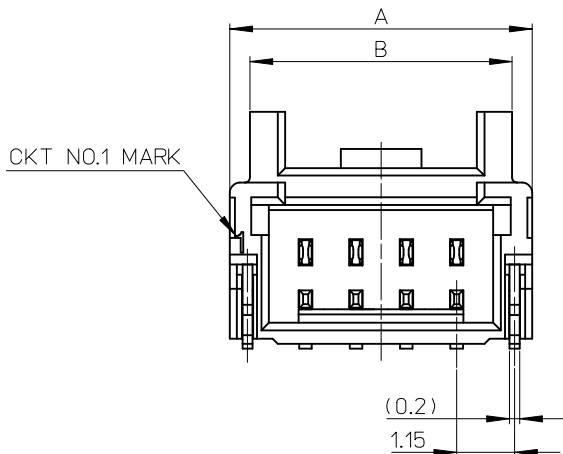
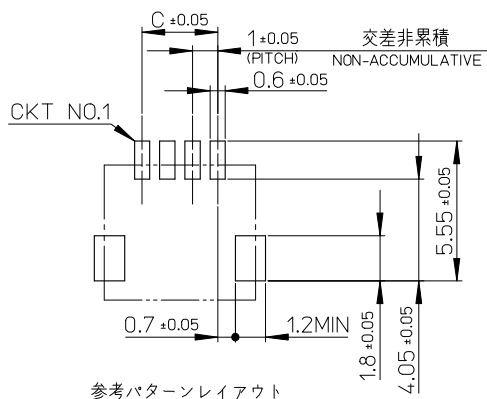
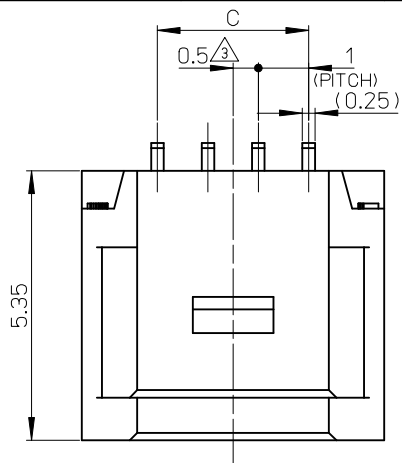
5

4

3

2

1



番号 NO.	部品 PART	材質 MATERIAL
①	ウェハー WAFER	耐熱ナイロン樹脂 UL94V-0 色:表参照 HEAT RESISTANCE NYLON .COLOR:SEE TABLE UL94V-0
②	ソルダーピン SOLDER PIN	りん青銅 PHOSPHOR BRONZE 錫メッキ: 1.0μmMIN. TIN ニッケルメッキ(下地): 1.0μmMIN. NICKEL(UNDER PLATING)
③	ネイル NAIL	黄銅 BRASS 錫メッキ: 1.0μmMIN. TIN ニッケルメッキ(下地): 1.0μmMIN. NICKEL(UNDER PLATING)

NOTES.

1. 嵌合相手: 501939-\*\*\*\*  
MATE WITH: 501939-\*\*\*\*
2. ソルダーピン及びネイル平坦度は、0.1MAX.  
SOLDER PIN AND NAIL COPLANARITY TO BE 0.1MAX.
- △ 極数=偶数に適用  
APPLY FOR CKT SIZE=EVEN
4. ELV AND RoHS COMPLIANT.

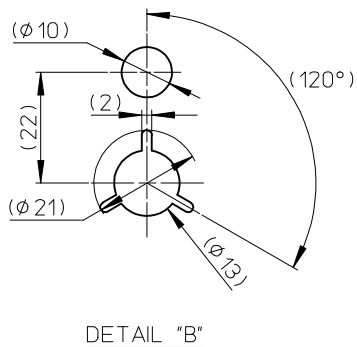
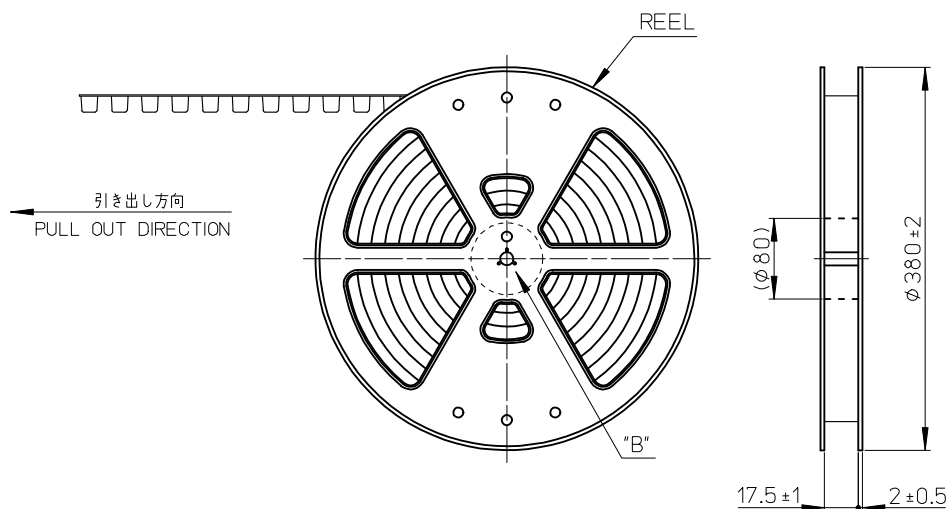
4.0	5.2	7.0	5
3.0		6.0	4
2.0	4.2	5.0	3
C	B	A	極数 CIRCUITS

CONNECTOR SERIES No. 501953-\*\*\*9

REVISED EC NO: J2010-0339 DRWN: TAKAGAWA01 2009/09/01 CHKD: MATSUMOTO 2009/09/01 APPR: HIRATA 2009/09/01	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY NYOSHIDA	DATE 2005/09/16	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y 1-ROW R/A POSI-LOCK			
	10 OVER 30 UNDER	±0.25	CHECKED BY AMIZUMURA	DATE 2005/09/16				
	30 OVER	±0.3	APPROVED BY MYAGI	DATE 2005/09/16	MOLEX INCORPORATED			
ANGULAR ±3 °		MATERIAL NO. SEE SHEET 2		DOCUMENT NO. SD-501953-001				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

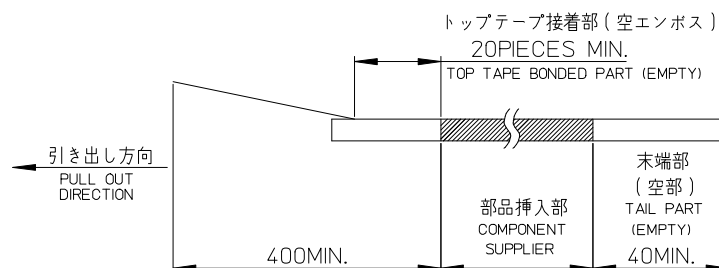
紫 PA46 VIOLET	橙 PA46 ORANGE	茶 PA46 BROWN	緑 PA46 GREEN	色 COLOR	
501953-0597	501953-0587	501953-0577	501953-0567	5	
501953-0497	501953-0487	501953-0477	501953-0467	4	
501953-0397	501953-0387	501953-0377	501953-0367	3	
EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	極数	
オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	CIRCUITS	
CONNECTOR SERIES No. 501953-***9					
青 PA46 BLUE	黄 PA46 YELLOW	赤 PA46 RED	黒 PA46 BLACK	自然色 PA6T NATURAL	色 COLOR
501953-0547	501953-0537	501953-0527		501953-0507	5
501953-0447	501953-0437	501953-0427	501953-0417	501953-0407	4
501953-0347	501953-0337	501953-0327	501953-0317	501953-0307	3
EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	極数
オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	CIRCUITS
CONNECTOR SERIES No. 501953-***9					

REVISED EC NO: J2010-0339 DRWN: TAKAGAWA01 2009/09/01 CHKD: MATSUMOTO 2009/09/01 APPR: HIRATA 2009/09/01	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	DRAWN BY NYOSHIDA	DATE 2005/09/16	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y 1-ROW R/A POSI-LOCK  MOLEX INCORPORATED  SEE TABLE SD-501953-001				
		10 OVER 30 UNDER	± ---	CHECKED BY AMIZUMURA	DATE 2005/09/16					
		30 OVER	± ---	APPROVED BY MYAGI	DATE 2005/09/16					
ANGULAR ± --- °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.	DOCUMENT NO.					
				SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



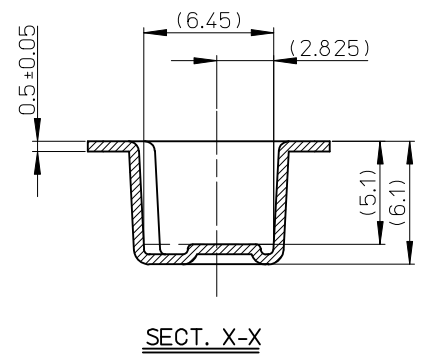
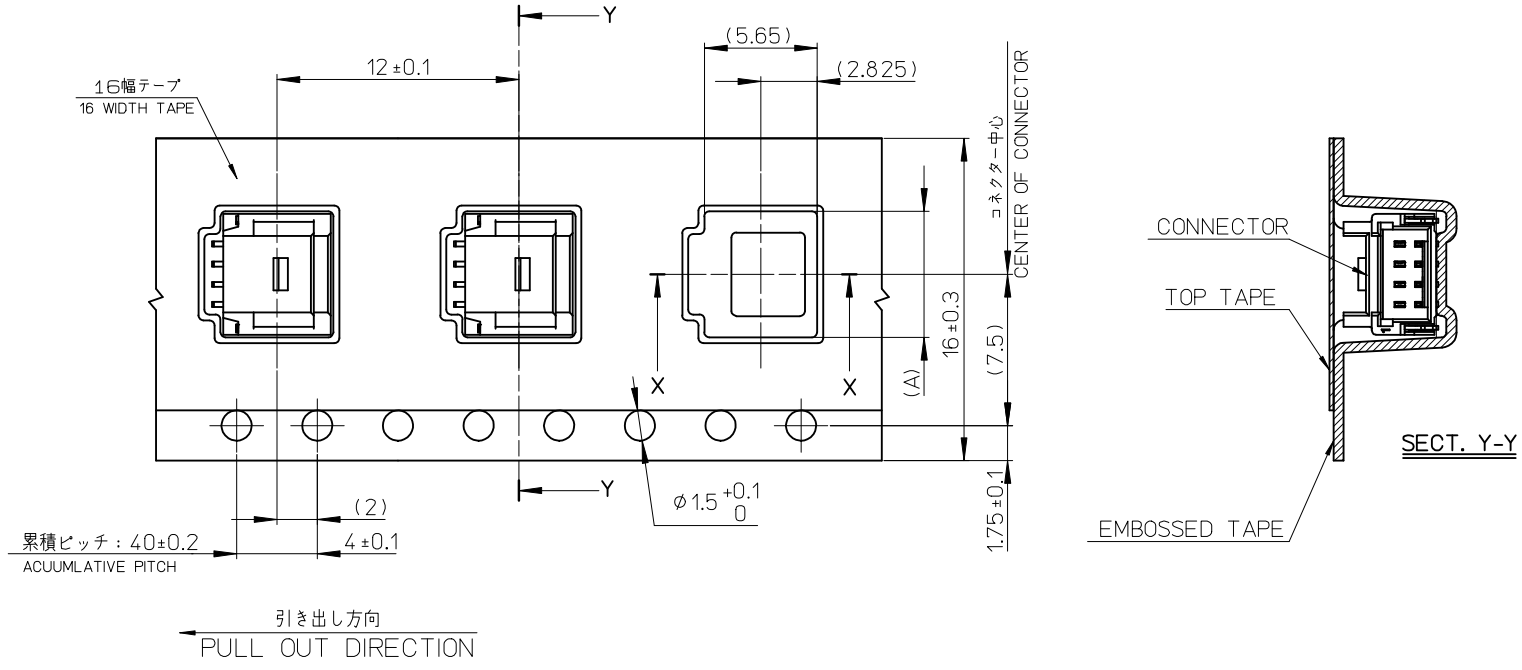
NOTES

- 製品詳細寸法は製品単体図面を参照して下さい。  
FOR DETAIL OF CONNECTOR DIMENSIONS, PLEASE SEE THE DRAWING OF CONNECTOR ITSELF (NOT PACKAGED).
- 梱包数量: 1300個/リール  
NUMBER OF CONNECTORS: 1300PIECES/REEL
- リードテープ長さ  
LEAD TAPE LENGTH



- 材料  
MATERIAL  
キャリアテープ: ポリスチレン  
CARRIER TAPE: POLYSTYRENE  
トップテープ: PET、その他  
TOP TAPE: PET, OTHER  
リール: ポリスチレン<リサイクル材を含む>  
REEL: POLYSTYRENE <RECYCLE MATERIAL CONTAINED >
5. ELV AND RoHS COMPLIANT.
- ハイバリア梱包 (シリカゲル入り) 対応品である。(501953-\*\*07除く)  
THIS PRODUCT IS HIGH BARRIER PACKAGE.(WITH SILICAGEL)  
(BESIDES 501953-\*\*07)
- 開梱後の保管条件に注意のこと。(ハイバリア品対象: PS-501940-001参照)  
REFER TO PS-501940-001(HIGH BARRIER PRODUCT)  
FOR CONDITIONS AFTER OPEN.

REVISED EC NO: J2010-0339 DRWN: TAKAGAWA01 2009/09/01 CHKD: MATSUMOTO 2009/09/01 APPR: HIRATA 2009/09/01	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY NYOSHIDA	DATE 2005/09/16	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y 1-ROW R/A EMBSTP PKG		
	10 OVER 30 UNDER	±0.25	CHECKED BY AMIZUMURA	DATE 2005/09/16	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY MYAGI	DATE 2005/09/16			
ANGULAR ±3 °		MATERIAL NO. SEE SHEET 3		DOCUMENT NO. SD-501953-002		SHEET NO. 1 OF 3	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



7.3	5
6.3	4
5.3	3
(A)	極数 CIRCUITS

CONNECTOR SERIES No. 501953-\*\*\*9

REVISED EC NO: J2010-0339 DRWN: TAKAGAWA01 2009/09/01 CHKD: MATSUMOTO 2009/09/01 APPR: HIRATA 2009/09/01	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY NYOSHIDA	DATE 2005/09/16	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y 1-ROW R/A EMBSTP PKG	
	10 OVER 30 UNDER	±0.25	CHECKED BY AMIZUMURA	DATE 2005/09/16	MOLEX INCORPORATED	
	30 OVER	±0.3	APPROVED BY MYAGI	DATE 2005/09/16	MATERIAL NO. SEE SHEET 3	DOCUMENT NO. SD-501953-002
	ANGULAR ±3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

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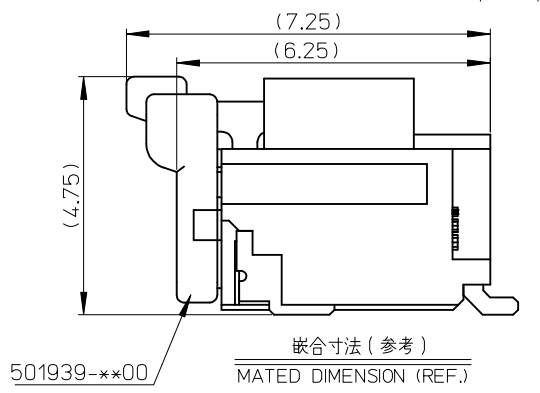
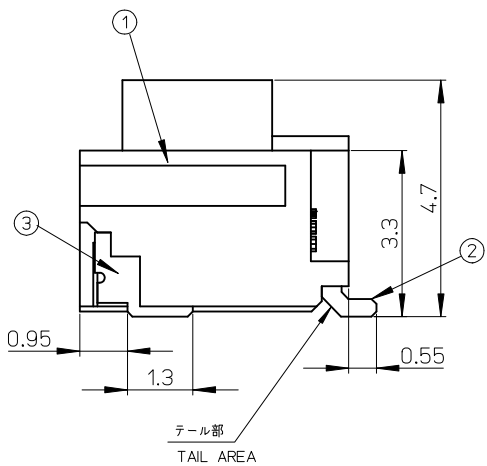
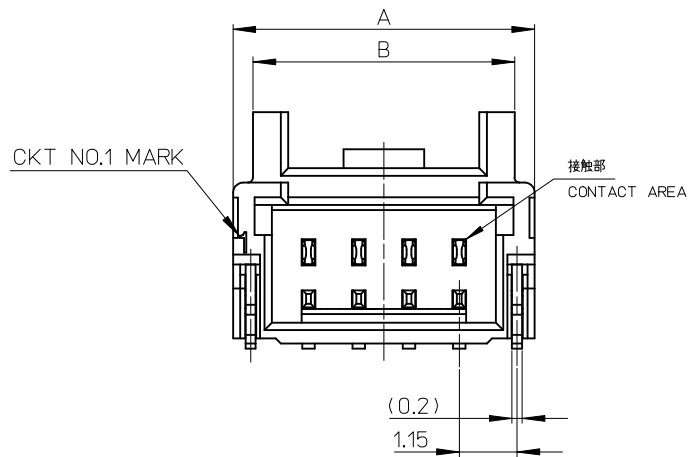
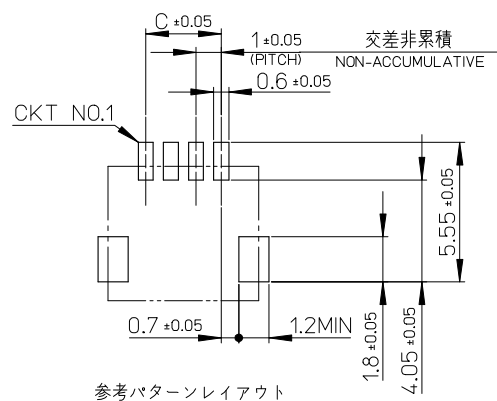
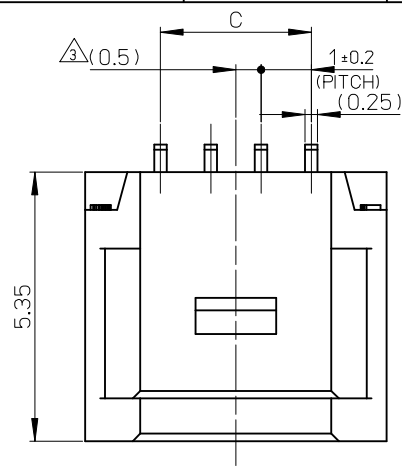
紫 VIOLET	橙 ORANGE	茶 BROWN	緑 GREEN	色 COLOR
501953-0597	501953-0587	501953-0577	501953-0567	5
501953-0497	501953-0487	501953-0477	501953-0467	4
501953-0397	501953-0387	501953-0377	501953-0367	3
EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS

CONNECTOR SERIES No. 501953-\*\*\*9

青 BLUE	黄 YELLOW	赤 RED	黒 BLACK	自然色 NATURAL	色 COLOR
501953-0547	501953-0537	501953-0527		501953-0507	5
501953-0447	501953-0437	501953-0427	501953-0417	501953-0407	4
501953-0347	501953-0337	501953-0327	501953-0317	501953-0307	3
EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS

CONNECTOR SERIES No. 501953-\*\*\*9

REVISED EC NO: J2010-0339 DRWN: TAKAGAWA01 2009/09/01 CHKD: MATSUMOTO 2009/09/01 APPR: HIRATA 2009/09/01	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±---	DRAWN BY NYOSHIDA	DATE 2005/09/16	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y 1-ROW R/A EMBSTP PKG			
		10 OVER 30 UNDER	±---	CHECKED BY AMIZUMURA	DATE 2005/09/16	MOLEX INCORPORATED			
		30 OVER	±---	APPROVED BY MYAGI	DATE 2005/09/16	DOCUMENT NO. SD-501953-002		SHEET NO. 3 OF 3	
REV		ANGULAR ±--- °		MATERIAL NO. SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3					



番号 NO.	部品 PART	材質 MATERIAL
①	ウエハー WAFER	耐熱ナイロン樹脂 UL94V-0 色:表参照 HEAT RESISTANCE NYLON .COLOR:SEE TABLE UL94V-0
②	ソルダーピン SOLDER PIN	りん青銅 PHOSPHOR BRONZE 金メッキ (接触部): 0.1μm MIN. GOLD PLATING (CONTACT AREA) 金メッキ (テール部): 0.05μm MIN. GOLD PLATING (TAIL AREA) ニッケルメッキ (下地): 1.0μmMIN. NICKEL(UNDER PLATING)
③	ネイル NAIL	黄銅 BRASS 錫メッキ: 1.0μmMIN. TIN ニッケルメッキ (下地): 1.0μmMIN. NICKEL(UNDER PLATING)

- NOTES.
1. 嵌合相手: 501939-\*\*\*  
MATE WITH: 501939-\*\*\*
  2. ソルダーピン及びネイル平坦度は、0.1MAX.  
SOLDER PIN AND NAIL COPLANARITY TO BE 0.1MAX.
  3. 極数=偶数に適用  
APPLY FOR CKT SIZE=EVEN
  4. ELV AND RoHS COMPLIANT.


4.0	5.2	7.0	5
3.0		6.0	4
2.0	4.2	5.0	3
C	B	A	極数 CIRCUITS

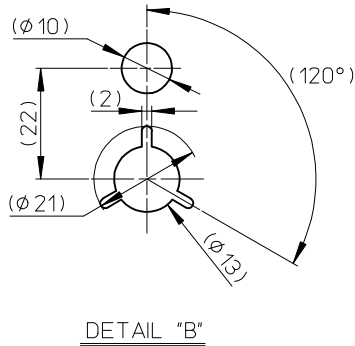
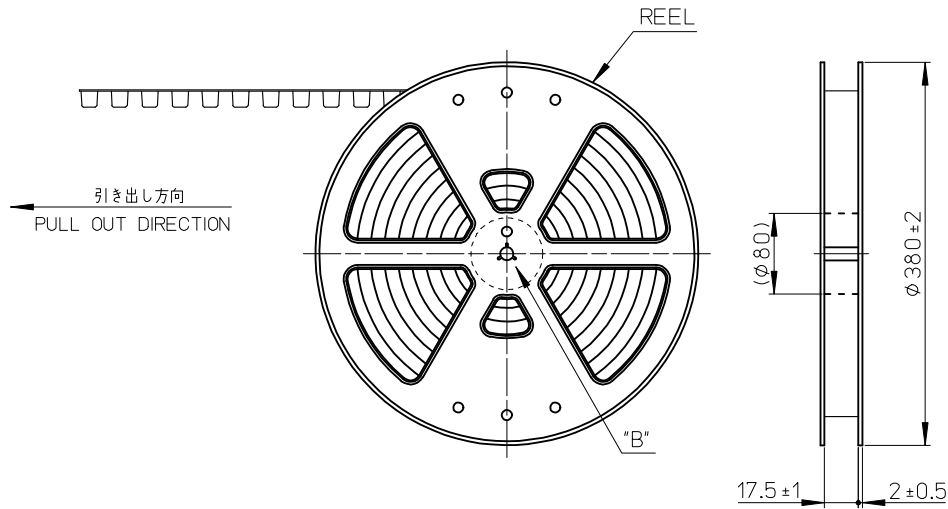
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REVISED EC NO: J2016-1063 DR: WNR/TAKAKA02 2016/04/07 CHKD: SAKI/YAMA 2016/04/08 APPR: IKANEKO 2016/04/28	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		CONNECTOR SERIES No. 501953-***6		
	0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	0.25 OVER	0.5 UNDER	±0.05	KCHIKANO	2014/12/25	10:1	METRIC	◎
	0.5 OVER	1.0 UNDER	±0.1	CHECKED BY	DATE	TITLE		
1.0 OVER	10 UNDER	±0.2	KASAKAWA	2014/12/25	1.0 WIRE TO BOARD CONN. WAFER ASS'Y 1-ROW R/A POSI-LOCK			
10 OVER	30 UNDER	±0.25	APPROVED BY	DATE				
30 OVER		±0.3	NUKITA	2015/01/16				
ANGULAR	±3 °		MATERIAL NO.		DOCUMENT NO.			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE	SEE SHEET 2		SD-501953-003		SHEET NO. 1 OF 2
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								

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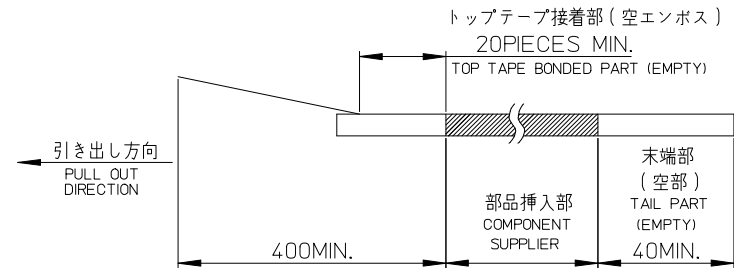
<del>紫 PA46 VIOLET</del>	<del>橙 PA46 ORANGE</del>	<del>茶 PA46 BROWN</del>	<del>緑 PA46 GREEN</del>	色 COLOR
<del>EMBOSSED PACKAGE</del>	<del>EMBOSSED PACKAGE</del>	<del>EMBOSSED PACKAGE</del>	<del>EMBOSSED PACKAGE</del>	5
<del>オーダー番号 ORDER NO.</del>	<del>オーダー番号 ORDER NO.</del>	<del>オーダー番号 ORDER NO.</del>	<del>オーダー番号 ORDER NO.</del>	4
<del>EMBOSSED PACKAGE</del>	<del>EMBOSSED PACKAGE</del>	<del>EMBOSSED PACKAGE</del>	<del>EMBOSSED PACKAGE</del>	3
<del>オーダー番号 ORDER NO.</del>	<del>オーダー番号 ORDER NO.</del>	<del>オーダー番号 ORDER NO.</del>	<del>オーダー番号 ORDER NO.</del>	極数 CIRCUITS
CONNECTOR SERIES No. 501953-***9				
<del>青 PA46 BLUE</del>	<del>黄 PA46 YELLOW</del>	<del>赤 PA46 RED</del>	<del>黒 PA46 BLACK</del>	自然色 PA6T NATURAL
<del>EMBOSSED PACKAGE</del>	<del>EMBOSSED PACKAGE</del>	<del>EMBOSSED PACKAGE</del>	<del>EMBOSSED PACKAGE</del>	501953-0505
<del>オーダー番号 ORDER NO.</del>	<del>オーダー番号 ORDER NO.</del>	<del>オーダー番号 ORDER NO.</del>	<del>オーダー番号 ORDER NO.</del>	501953-0405
<del>EMBOSSED PACKAGE</del>	<del>EMBOSSED PACKAGE</del>	<del>EMBOSSED PACKAGE</del>	<del>EMBOSSED PACKAGE</del>	501953-0305
<del>オーダー番号 ORDER NO.</del>	<del>オーダー番号 ORDER NO.</del>	<del>オーダー番号 ORDER NO.</del>	<del>オーダー番号 ORDER NO.</del>	3
<del>EMBOSSED PACKAGE</del>	<del>EMBOSSED PACKAGE</del>	<del>EMBOSSED PACKAGE</del>	<del>EMBOSSED PACKAGE</del>	極数 CIRCUITS
<del>オーダー番号 ORDER NO.</del>	<del>オーダー番号 ORDER NO.</del>	<del>オーダー番号 ORDER NO.</del>	<del>オーダー番号 ORDER NO.</del>	<del>オーダー番号 ORDER NO.</del>
CONNECTOR SERIES No. 501953-***6				

REVISED EC NO: J2016-1063 DRWR: TANKA02 CHKD: SAKIYAMA APPR: KANEKO	2016/04/07 2016/04/08 2016/04/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		0.25 UNDER	UNDER	±0.03	DRAWN BY KCHIKANO	DATE 2014/12/25	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y 1-ROW R/A POSI-LOCK		
		0.25 OVER	0.5 UNDER	±0.05	CHECKED BY KASAKAWA	DATE 2014/12/25	 SD-501953-003		
		0.5 OVER	1.0 UNDER	±0.1	APPROVED BY NUKITA	DATE 2015/01/16			
		1.0 OVER	10 UNDER	±0.2	MATERIAL NO.		DOCUMENT NO.	SHEET NO.	
10 OVER	30 UNDER	±0.25	SEE CHART		SD-501953-003	2 OF 2			
30 OVER		±0.3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
ANGULAR	±3 °		SIZE A3						



NOTES

- 製品詳細寸法は製品単体図面を参照して下さい。  
FOR DETAIL OF CONNECTOR DIMENSIONS, PLEASE SEE THE DRAWING OF CONNECTOR ITSELF (NOT PACKAGED).
- 梱包数量: 1300個/リール  
NUMBER OF CONNECTORS: 1300PIECES/REEL
- リードテープ長さ  
LEAD TAPE LENGTH

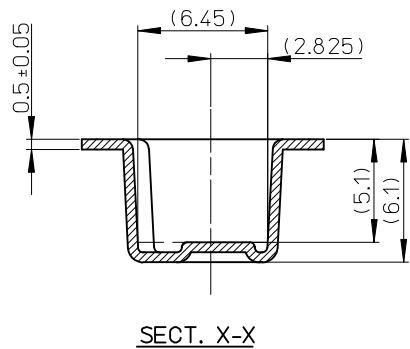
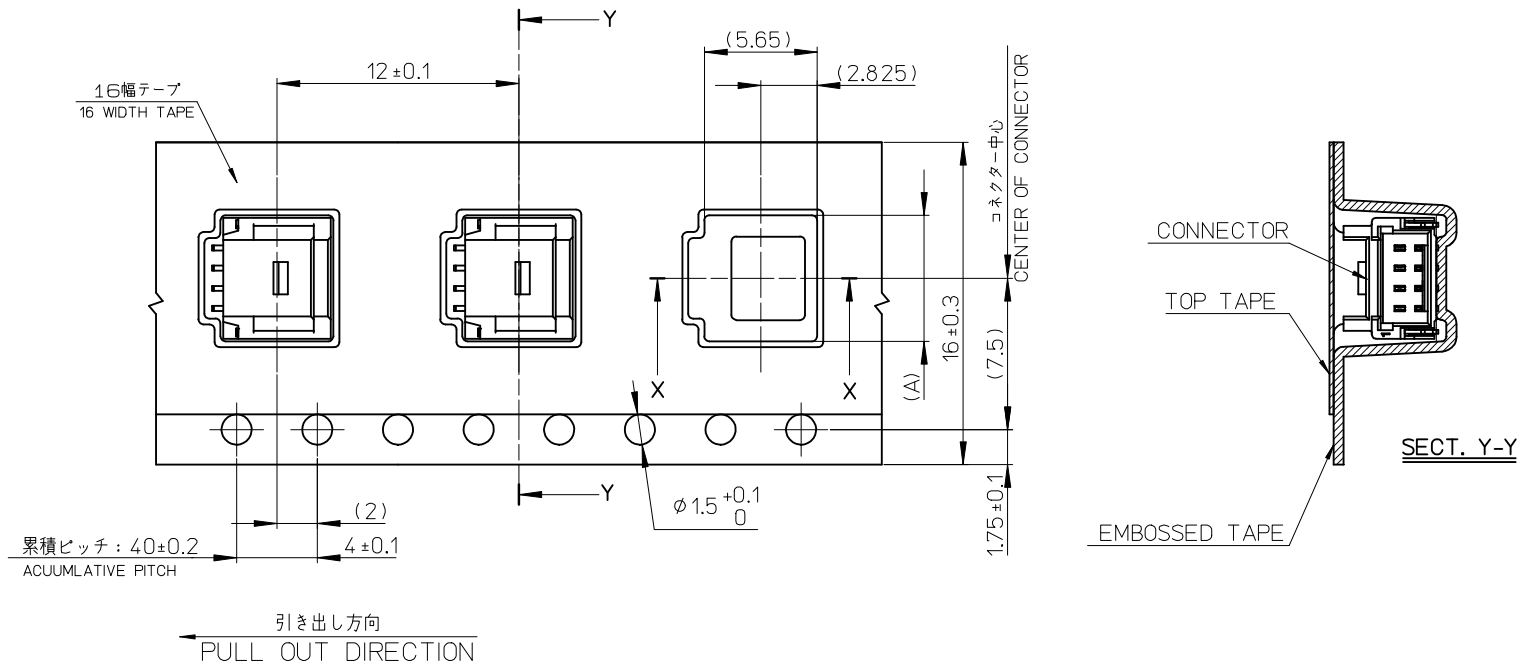


- 材料  
MATERIAL  
キャリアテープ: ポリスチレン  
CARRIER TAPE: POLYSTYRENE  
トップテープ: PET、その他  
TOP TAPE: PET, OTHER  
リール: ポリスチレン<リサイクル材を含む>  
REEL: POLYSTYRENE <RECYCLE MATERIAL CONTAINED >
5. ELV AND RoHS COMPLIANT.
- ハイバリア梱包 (シリカゲル入り) 対応品である。(501953-\*\*07除く)  
THIS PRODUCT IS HIGH BARRIER PACKAGE. (WITH SILICAGEL) (BESIDES 501953-\*\*07)
- 開梱後の保管条件に注意のこと。(ハイバリア品対象: PS-501940-001参照)  
REFER TO PS-501940-001 (HIGH BARRIER PRODUCT) FOR CONDITIONS AFTER OPEN.

REVISED EC NO: J2016-1063 DRWR: TANAKA02 2016/04/07 CHKD: SAKIYAMA 2016/04/08 APPR: KANEKO 2016/04/28	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	± 0.03	DRAWN BY	DATE	TITLE		
	0.25 OVER	0.5 UNDER	± 0.05	KCHIKANO	2014/12/25	1.0 WIRE TO BOARD CONN. WAFER ASS'Y 1-ROW R/A EMBSTP PKG		
	0.5 OVER	1.0 UNDER	± 0.1	CHECKED BY	DATE			
	1.0 OVER	10 UNDER	± 0.2	KASAKAWA	2014/12/25			
	10 OVER	30 UNDER	± 0.25	APPROVED BY	DATE			
30 OVER		± 0.3	NUKITA	2015/01/16	MATERIAL NO.	DOCUMENT NO.	SHEET NO.	
ANGULAR	± 3 °		SEE SHEET 3		SD-501953-004		1 OF 3	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



CONFIDENTIAL




7.3	5
6.3	4
5.3	3
(A)	極数 CIRCUITS

CONNECTOR SERIES No. 501953-\*\*\*6

<b>REVISED</b> EC NO: J2016-1063 DRWR: TANKA02 2016/04/07 CHKD: SAKIYAMA 2016/04/08 APPR: KANEKO 2016/04/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
			MM ONLY	---	METRIC		
	DESCRIPTION	0.25 UNDER	UNDER	± 0.03	DRAWN BY	DATE	TITLE
		0.25 OVER	0.5 UNDER	± 0.05	KCHIKANO	2014/12/25	1.0 WIRE TO BOARD CONN. WAFER ASS'Y 1-ROW R/A EMBSTP PKG
		0.5 OVER	1.0 UNDER	± 0.1	CHECKED BY	DATE	
	1.0 OVER	10 UNDER	± 0.2	KASAKAWA	2014/12/25	<b>molex</b> DOCUMENT NO. SD-501953-004 SHEET NO. 2 OF 3	
	10 OVER	30 UNDER	± 0.25	APPROVED BY	DATE		
	30 OVER		± 0.3	NUKITA	2015/01/16		
	ANGULAR	± 3 °		MATERIAL NO.			
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
A			A3	SEE SHEET 3			

CONFIDENTIAL

	紫 VIOLET	橙 ORANGE	茶 BROWN	緑 GREEN	色 COLOR
					5
					4
					3
	EMBOSSED PACKAGE	EMBOSSED PACKAGE	EMBOSSED PACKAGE	EMBOSSED PACKAGE	極数
	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	CIRCUITS
CONNECTOR SERIES No. 501953-***9					
	青 BLUE	黄 YELLOW	赤 RED	黒 BLACK	自然色 NATURAL
					501953-0505
					501953-0405
					501953-0305
	EMBOSSED PACKAGE	EMBOSSED PACKAGE	EMBOSSED PACKAGE	EMBOSSED PACKAGE	極数
	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	CIRCUITS

REVISED EC NO: J2016-1063 DRWR: TANKA02 CHKD: SAKIYAMA APPR: KANEKO	2016/04/07 2016/04/08 2016/04/28	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	TITLE		
		0.25 OVER	0.5 UNDER	±0.05	KCHIKANO	2014/12/25	1.0 WIRE TO BOARD CONN. WAFER ASS'Y 1-ROW R/A EMBSTP PKG		
		0.5 OVER	1.0 UNDER	±0.1	CHECKED BY	DATE			
		1.0 OVER	10 UNDER	±0.2	KASAKAWA	2014/12/25			
		10 OVER	30 UNDER	±0.25	APPROVED BY	DATE			
30 OVER		±0.3	NUKITA	2015/01/16	MATERIAL NO.	DOCUMENT NO.	SHEET NO.		
ANGULAR ±3 °			SEE CHART		SD-501953-004		3 OF 3		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				